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... Time to Failure (MTTF or **MTBF**) and useful ... 0 1/ 2/ 3/ t Figure 4. **Exponential** Distribution ... Voltage Acceleration Voltage **accelerated stress test** results can also ...

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... Mean Time to Failure (MTTF) or Mean Time Between Failures (**MTBF**) ... to various failure mechanisms (Normal, Lognormal, Weibull, and **Exponential** distributions are ...

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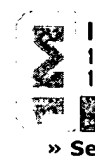
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